MSKSEMI 美森科













ESD

TVS

TSS

MOV

GDT

PLED

ESD5V0X1BL-MS

Product specification





Features

- 80W peak pulse power per line (tp = 8/20µs)
- SOD-882 package
- Replacement for MLV(0402)
- Bidirectional configurations
- Response time is typically < 1ns
- Low clamping voltage
- RoHS compliant
- Transient protection for data lines to IEC61000-4-2(ESD) ±25KV(air), ±25KV(contact); IEC61000-4-4 (EFT) 40A (5/50ns)

Mechanical Characteristics

- Mounting position: Any
- Qualified max reflow temperature:260 °C
- Device meets MSL 1 requirements
- SOD-882 without plating

Applications

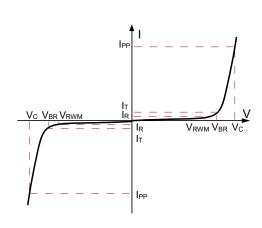
- Cellular phones
- Portable devices
- Digital cameras
- Power supplies

Reference News

SOD-882	PIN Configuration	Marking	
	Pin 1 Circuit Diagram	L*	

Electronics Parameter

Symbol	Parameter		
VRWM	Peak Reverse Working Voltage		
I R	Reverse Leakage Current @ VRWM		
V _{BR}	Breakdown Voltage @ Iτ		
Г	Test Current		
I PP	Maximum Reverse Peak Pulse Current		
Vc	Clamping Voltage @ IPP		
P _{PP}	Peak Pulse Power		
Cı	Junction Capacitance		
F	Forward Current		
VF	Forward Voltage @ IF		





Electrical characteristics per line@25℃ (unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Units
Peak Reverse Working Voltage	VRWM			5		V
Breakdown Voltage	VBR	lt = 1mA	5.6			V
Reverse Leakage Current	lR	V _{RWM} = 5V T=25°C			1.0	μΑ
Clamping Voltage	VcL	IPP=16A t _P =100ns		24		٧
Clamping Voltage	Vc	Ipp=1.0A			10	V
Clamping Voltage	Vc	IPP=4.0A			15	V
Junction Capacitance	Cj	V _R =0V f = 1MHz		0.30	0.50	pF

Absolute maximum rating@25℃

Rating	Symbol	Value	Units
Peak Pulse Power (t _P =8/20μs)	P _{pp}	80	W
Operating Temperature	TJ	-55 to 150	°C
Storage Temperature	Тѕтс	-55 to 150	$^{\circ}$



TypicalCharacteristics

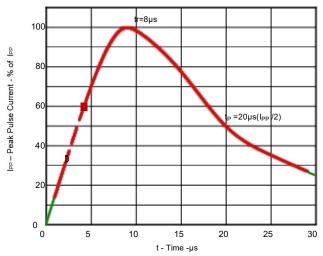


Fig 1.Pulse Waveform(8/20µs)

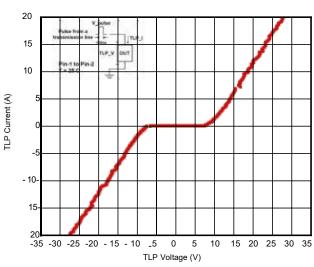


Fig 3. TLP Measurement

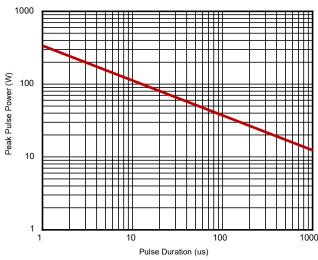


Fig 5. Non Repetitive Peak Pulse Power vs. Pulse time

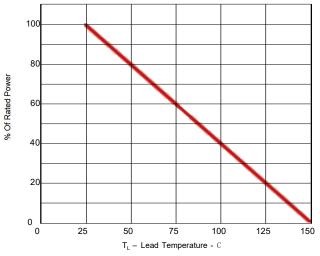


Fig 2.Power Derating Curve

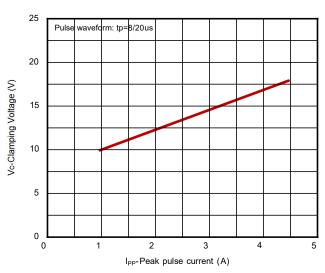


Fig 4. Clamping voltage vs. Peak pulse current

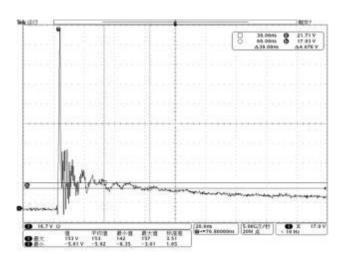


Fig 6.ESD Clamp[ing Voltage] (IEC61000-4-2 +8KV contact)

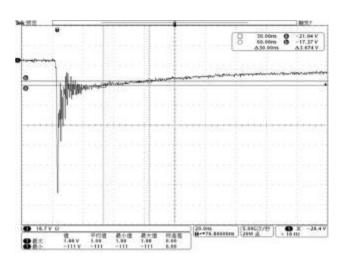
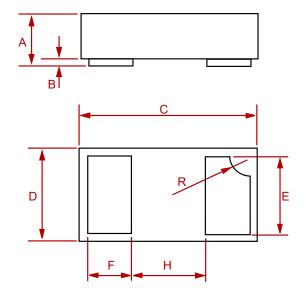


Fig 7.ESD Clamp[ing Voltage] (IEC61000-4-2 -8KV contact)

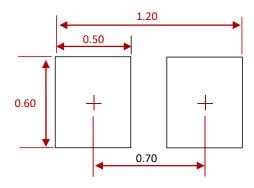


PACKAGEMECHANICALDATA



	Inches		Millimeters		
Dim	MIN	MAX	MIN	MAX	
А	0.0125	0.02	0.32	0.52	
В	0.000	0.002	0.00	0.05	
С	0.037	0.043	0.95	1.080	
D	0.022	0.027	0.55	0.680	
E	0.016	0.024	0.40	0.60	
F	0.008	0.012	0.20	0.30	
Н	0.015Typ.		0.40	Тур.	
R	0.001	0.005	0.05	0.15	

Suggested Pad Layout



NOTES:

- 1. CONTROLLING DIMENSIONS ARE IN MILLIMETERS (ANGLES IN DEGREES).
- 2. THIS LAND PATTERN IS FOR REFERENCE PURPOSES ONLY. CONSULT YOUR MANUFACTURING GROUP TO ENSURE YOUR COMPANY'S MANUFACTURING GUIDELINES ARE MET.

Order information

Orderable Device	Package	Packing Option
ESD5V0X1BL-MS	SOD-882	10000PCS



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